Pch -100V -13A Power MOSFET

| V _{DSS} | -100V |
|----------------------------|-------|
| R _{DS(on)} (Max.) | 200mΩ |
| I _D | ±13A |
| P _D | 20W |

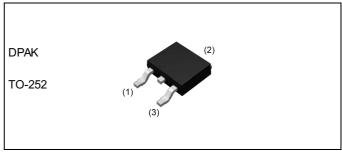
● Features

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating; RoHS compliant

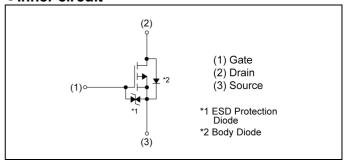
Application

Switching

Outline



Inner circuit



Packaging specifications

| | Packing | Embossed Tape |
|------|---------------------------|------------------|
| | Reel size (mm) | 330 |
| _ | Tape width (mm) | 16 |
| Type | Basic ordering unit (pcs) | 2500 |
| | Taning and | TL |
| | Taping code | TL1 |
| | Marking | RD3P130SP |

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|--------------------|-------------|------|
| Drain - Source voltage | V _{DSS} | -100 | V |
| Continuous drain current | I _D *1 | ±13 | Α |
| Pulsed drain current | I _{DP} *2 | ±52 | Α |
| Gate - Source voltage | V _{GSS} | ±20 | V |
| Power dissipation | P _D *3 | 20 | W |
| Junction temperature | T _j | 150 | °C |
| Operating junction and storage temperature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Parameter | Symbol | Values | | | Lleit |
|-------------------------------------|----------------------|--------|------|------|-------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} *3 | - | - | 6.25 | °C/W |

● Electrical characteristics (T_a = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit | |
|--|---|---|--------|-------|------|-------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic | |
| Drain - Source breakdown voltage | V _{(BR)DSS} | $V_{GS} = 0V$, $I_D = -1mA$ | -100 | - | - | V | |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}} I_{D} = -1 \text{mA}$ referenced to 25°C | | - | -91.3 | - | mV/°C | |
| Zero gate voltage drain current | I_{DSS} $V_{DS} = -100V$, $V_{GS} = 0V$ | | - | - | -1 | μA | |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | 1 | ±10 | μA | |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = -10V$, $I_{D} = -1mA$ | -1.0 | 1 | -2.5 | V | |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$ | I _D = -1mA referenced to 25°C | - | 3.0 | - | mV/°C | |
| | | V _{GS} = -10V, I _D = -6.5A | - | 135 | 200 | | |
| Static drain - source on - state resistance | R _{DS(on)} *4 | V _{GS} = -4.5V, I _D = -6.5A | - | 150 | 220 | mΩ | |
| | | $V_{GS} = -4.0V, I_D = -6.5A$ | - | 155 | 230 | 1 | |
| Gate resistance | R _G f = 1MHz, open drain | | - | 6.0 | 1 | Ω | |
| Forward Transfer Admittance | Y _{fs} *4 | V _{DS} = -10V, I _D = -13A | 10 | - | - | S | |

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s , Duty cycle \leq 1%

^{*3} T_C=25°C

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C)

| Daramatar | Cymahal | Conditions | Values | | | Unit |
|--|-----------------------|-------------------------------------|----------------|------|---|------|
| Parameter | Symbol | Conditions | Min. Typ. Max. | | | |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 2400 | - | _ |
| Output capacitance | C _{oss} | V _{DS} = -25V | - | 100 | - | pF |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | - | 65 | - | |
| Turn - on delay time | t _{d(on)} *4 | $V_{DD} \simeq -50V, V_{GS} = -10V$ | - | 20 | - | |
| Rise time | t _r *4 | I _D = -6.5A | - | 25 | - | no |
| Furn - off delay time ${\mathsf t_{\mathsf d(off)}}^{\star 4}$ | | R _L ~ 7.68Ω | - | 70 | - | ns |
| Fall time | t _f *4 | $R_G = 10\Omega$ | - | 60 | - | |

• Gate charge characteristics $(T_a = 25^{\circ}C)$

| | \ u | , | | | | |
|----------------------|--------------------|---|--------|------|------|-------|
| Parameter | Cymbol | Conditions | Values | | | Unit |
| raiametei | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Total gate charge | Qg*4 | Vnn ≃ -50V. | - | 40 | - | |
| Gate - Source charge | Q _{gs} *4 | V _{DD} ≃ -50V, I _D = -13A, V _{GS} = -10V | - | 6 | - | nC |
| Gate - Drain charge | Q _{gd} *4 | $V_{GS} = -10V$ | - | 6 | - | |

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Darameter | Symbol | Conditions | Values | | | l lait | |
|----------------------------|--------------------|---|--------|------|------|--------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit | |
| Continuous forward current | I _S *1 | T - 25°C | - | - | -13 | Α | |
| Pulse forward current | I _{SP} *2 | T _a = 25°C | - | - | -52 | Α | |
| Forward voltage | V _{SD} *4 | V _{GS} = 0V, I _S = -13A | - | - | -1.2 | V | |

Fig.1 Power Dissipation Derating Curve

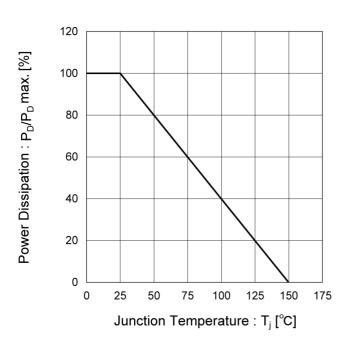


Fig.2 Maximum Safe Operating Area

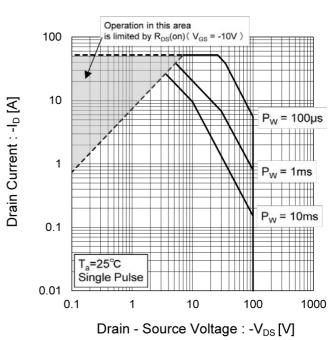


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

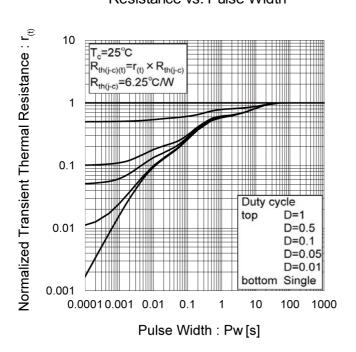


Fig.4 Single Pulse Maximum Power dissipation

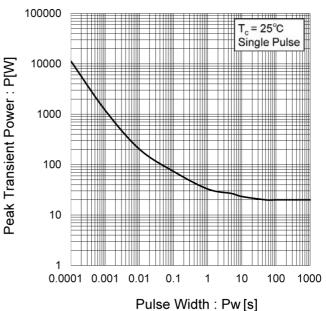


Fig.5 Typical Output Characteristics(I)

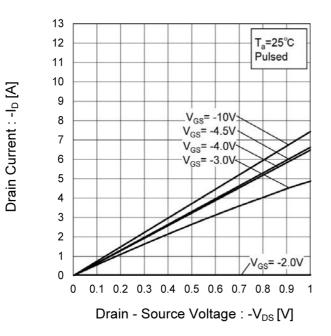


Fig.6 Typical Output Characteristics(II)

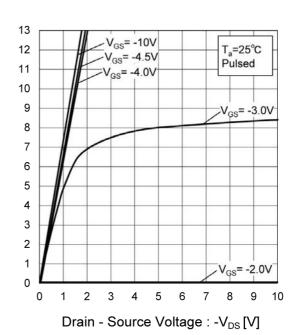
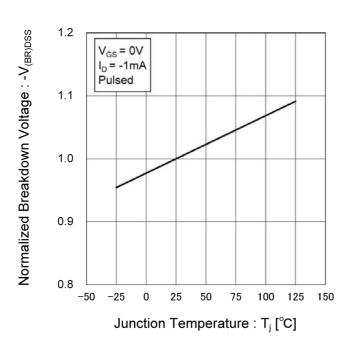


Fig.7 Breakdown Voltage vs.
Junction Temperature



Drain Current : -I_D [A]

Fig.8 Typical Transfer Characteristics

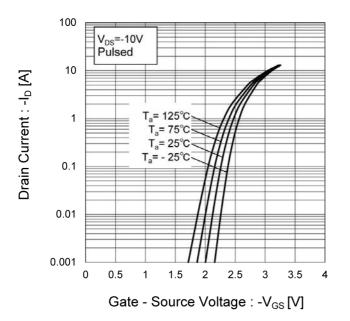


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

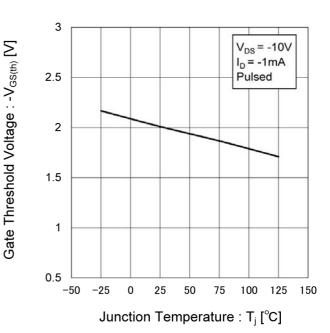
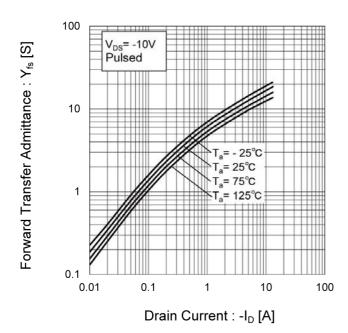


Fig.10 Forward Transfer Admittance vs.
Drain Current



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Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

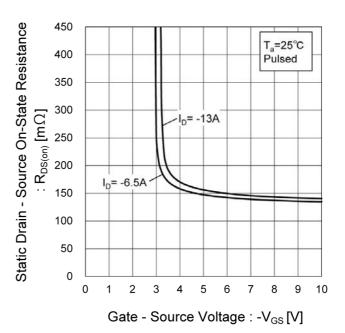
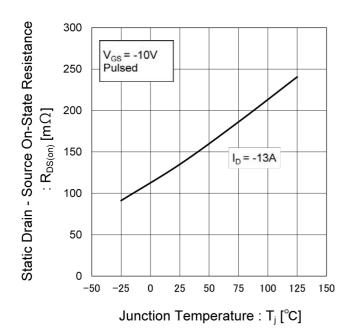


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



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Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

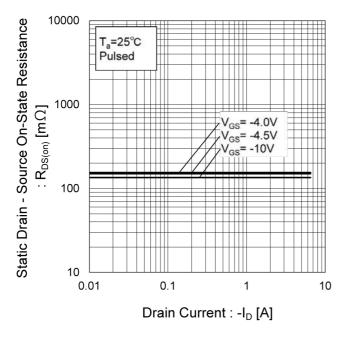


Fig.15 Static Drain - Source On - State
Resistance vs. Drain Current(II)

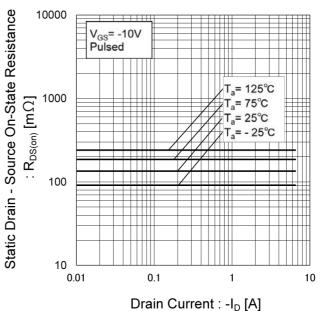


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

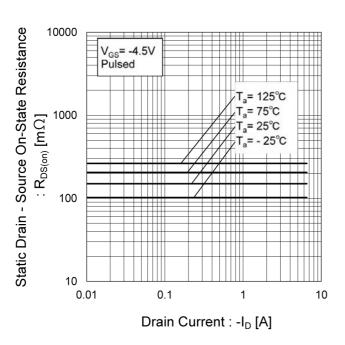


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

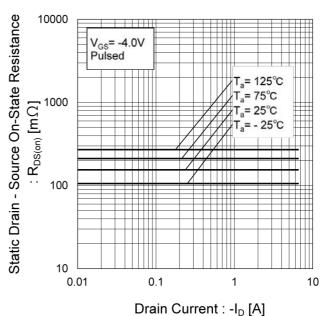


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

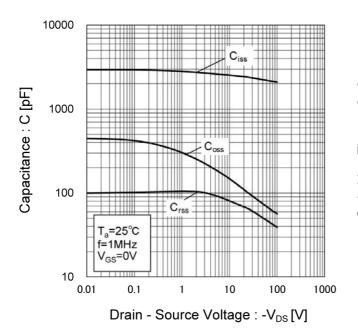


Fig.19 Switching Characteristics

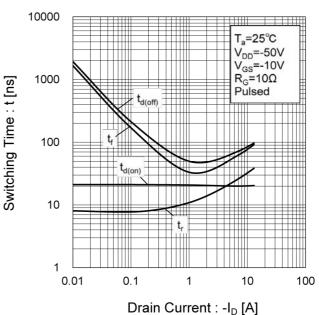


Fig.20 Dynamic Input Characteristics

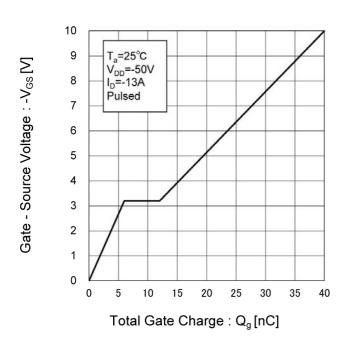
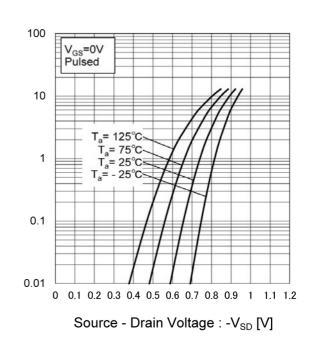


Fig.21 Source Current vs.

Source Drain Voltage



Source Current : -I_s [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

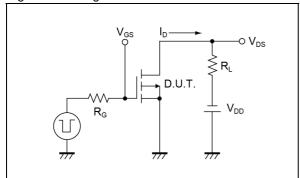


Fig.2-1 Gate Charge Measurement Circuit

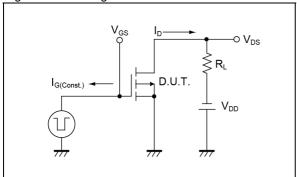


Fig.1-2 Switching Waveforms

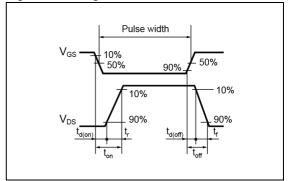
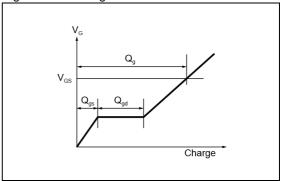
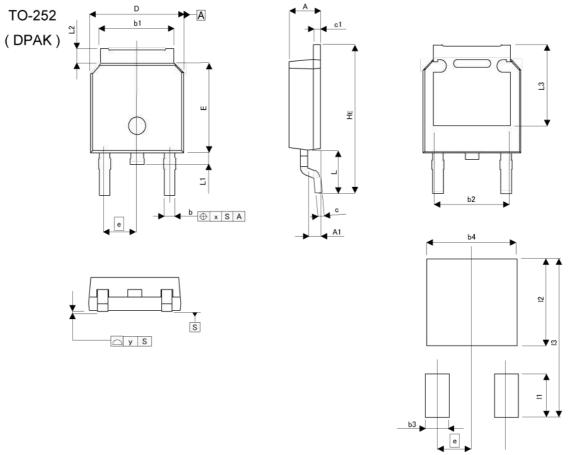


Fig.2-2 Gate Charge Waveform



ullet Dimensions (TL)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

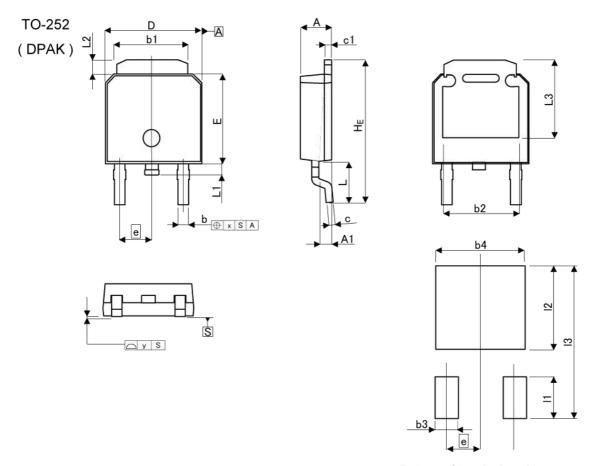
| DIM - | MILIME | ETERS | INC | HES |
|-------|--------|-------|-------|-------|
| DIIVI | MIN | MAX | MIN | MAX |
| Α | 2.10 | 2.30 | 0.083 | 0.091 |
| A1 | 0.70 | 1.10 | 0.028 | 0.043 |
| b | 0.65 | 0.85 | 0.026 | 0.033 |
| b1 | 5.10 | 5.40 | 0.201 | 0.213 |
| b2 | 5. | 10 | 0.2 | 201 |
| С | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 0.40 | 0.60 | 0.016 | 0.024 |
| D | 6.40 | 6.80 | 0.252 | 0.268 |
| е | 2. | 30 | 0.091 | |
| E | 6.00 | 6.40 | 0.236 | 0.252 |
| HE | 9.50 | 10.50 | 0.374 | 0.413 |
| L | 2. | 90 | 0.114 | |
| L1 | 0.70 | 0.90 | 0.028 | 0.035 |
| L2 | 0.70 | 1.30 | 0.028 | 0.051 |
| L3 | 5. | 30 | 0.2 | 209 |
| х | - | 0.10 | 160 | 0.004 |
| У | - | 0.10 | - | 0.004 |

| DIM | MILIM | ETERS | INC | HES |
|-----|----------|-------|-------------------|-------|
| DIN | MIN | MAX | MIN | MAX |
| b3 | ₽ | 1.10 | 622 | 0.043 |
| b4 | * | 5.40 | 5 .0 5 | 0.213 |
| 11 | <u> </u> | 2.90 | 72 | 0.114 |
| 12 | * | 5.50 | 5.00 | 0.217 |
| 13 | 2 | 10.50 | 021 | 0.413 |

Dimension in mm/inches



● Dimensions (TL1)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

| DIM | MILIME | ETERS | INCHES | |
|-----|--------|-------|--------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 2.20 | 2.40 | 0.087 | 0.094 |
| A1 | 0.70 | 1.10 | 0.028 | 0.043 |
| b | 0.60 | 0.90 | 0.024 | 0.035 |
| b1 | 5.20 | 5.50 | 0.205 | 0.217 |
| b2 | 4. | 80 | 0.1 | 89 |
| С | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 0.40 | 0.60 | 0.016 | 0.024 |
| D | 6.40 | 6.80 | 0.252 | 0.268 |
| е | 2. | 30 | 0.0 | 91 |
| E | 6.00 | 6.40 | 0.236 | 0.252 |
| HE | 9.40 | 10.40 | 0.370 | 0.409 |
| L | 2. | 90 | 0.114 | |
| L1 | 0.60 | 1.00 | 0.024 | 0.039 |
| L2 | 0.70 | 1.30 | 0.028 | 0.051 |
| L3 | 5. | 30 | 0.209 | |
| Х | | 0.25 | | 0.010 |
| у | 8 | 0.10 | (5) | 0.004 |
| - I | MILIME | ETERS | INC | HES |
| DIM | MIN | MAX | MIN | MAX |
| b3 | - | 1.15 | S#6 | 0.045 |
| b4 | | 5.55 | 0.50 | 0.219 |
| 11 | - | 2.77 | S 1980 | 0.109 |
| 12 | 7. | 5.50 | (5) | 0.217 |
| 13 | # | 10.40 | 740 | 0.409 |

Dimension in mm/inches



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|---------|-----------|------------|----------|
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| CLASSIV | CLASSIII | CLASSⅢ | CLASSII |

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
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